

ABSTRACT

WAFER PROCESSING METHOD

A wafer processing method includes a liquid supplying step of supplying a liquid to the front side of a wafer, a close contact making step of pressing a protective film against the front side of the wafer with the liquid interposed therebetween, thereby bringing the protective film into close contact with the front side of the wafer, a protective member fixing step of covering the protective film with a protective member formed from a liquid resin curable by external stimulus, thereby fixing the protective member through the protective film to the front side of the wafer, a grinding step of grinding the back side of the wafer to reduce the thickness of the wafer, and a peeling step of peeling the protective film and the protective member from the wafer thinned by the grinding step.

(Figure 1)